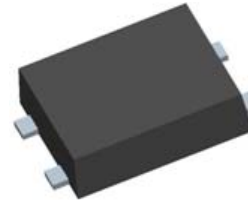


### Features

- Low profile package
- Ideal for automated placement
- Ultrafast reverse recovery time
- Low power losses, high efficiency
- Low forward voltage drop
- High surge capability
- High temperature soldering:  
260°C/10 seconds at terminals
- Component in accordance to  
RoHS 2002/95/1 and WEEE 2002/96/EC

Patented Product



MBF

### Mechanical Date

- **Case:** MBF Molded plastic body over low VF Schottky barrier chips
- **Terminals:** Solder plated, solderable per JESD22-B102
- **Polarity:** Polarity symbols marked on body

### Major Ratings and Characteristics

$I_{F(AV)}$	1.0 A
$V_{RRM}$	20V to 100V
$I_{FSM}$	30 A
$V_F$	0.44 V, 0.63 V, 0.75V
$T_j \text{ max.}$	125 °C

### Maximum Ratings & Thermal Characteristics

( $T_A = 25\text{ °C}$  unless otherwise noted)

Items	Symbol	LMB12F	LMB14F	LMB16F	LMB18F	LMB110F	UNIT
Maximum repetitive peak reverse voltage	$V_{RRM}$	20	40	60	80	100	V
Maximum RMS voltage	$V_{RMS}$	14	28	42	56	70	V
Maximum DC blocking voltage	$V_{DC}$	20	40	60	80	100	V
Maximum average forward output rectified current at $T_A=30\text{ °C}$	$I_{F(AV)}$	1.0					A
Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load (JEDEC Method)	$I_{FSM}$	30					A
Thermal resistance from junction to ambient per leg <sup>(1)</sup>	$R_{\theta JA}$	85					°C/W
Thermal resistance from junction to lead per leg <sup>(1)</sup>	$R_{\theta JL}$	20					°C/W
Operating junction temperature range	$T_J$	-55 to +125					°C
Storage temperature range	$T_{STG}$	-55 to +125					°C

Note 1: Units mounted on P.C.B. with 0.5×0.5" (13×13mm) pads

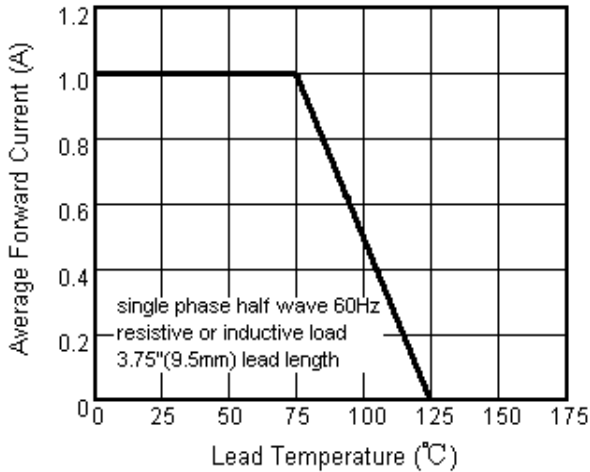
### Electrical Characteristics ( $T_A = 25\text{ °C}$ unless otherwise noted)

Items	Test conditions	Symbol	LMB12F~ LMB14F	LMB16F	LMB18F~ LMB110F	UNIT
Instantaneous forward voltage per leg	$I_F=1.0A$ <sup>(2)</sup>	$V_F$	0.44	0.63	0.75	V
Reverse current per leg	$V_R=V_{DC}$ $T_j=25\text{ °C}$ $T_j=100\text{ °C}$	$I_R$	0.5 20			mA

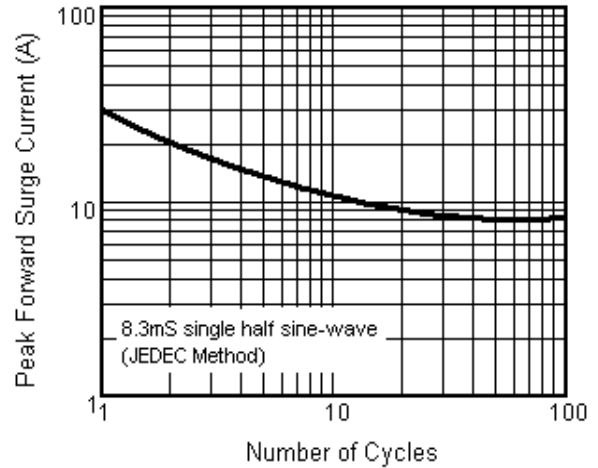
Note 2: Pulse test:300µs pulse width,1% duty cycle.

**Characteristic Curves** ( $T_A=25\text{ }^\circ\text{C}$  unless otherwise noted)

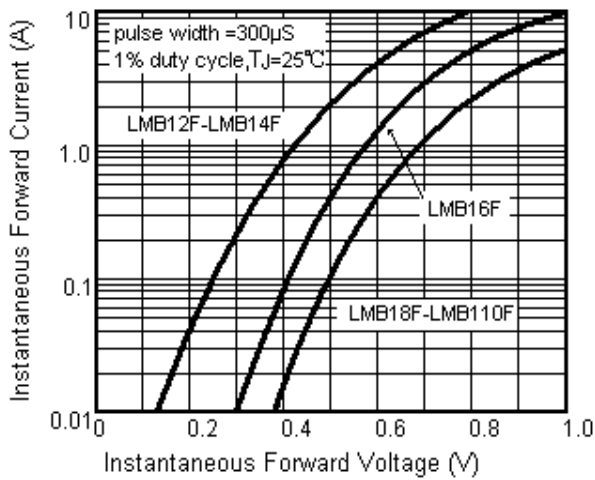
**Fig.1 Forward Current Derating Curve**



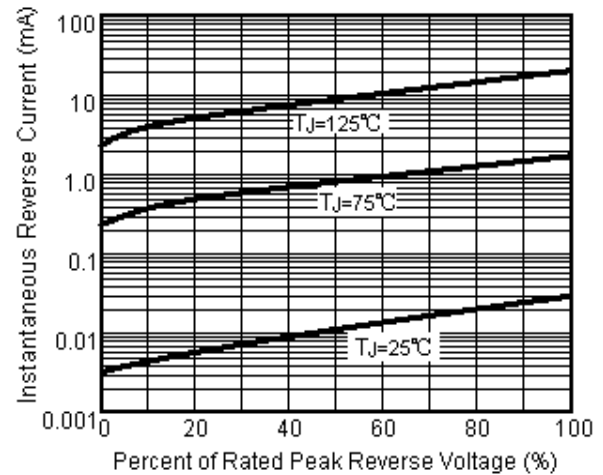
**Fig.2 Maximum Non-Repetitive Peak Forward Surge Current**



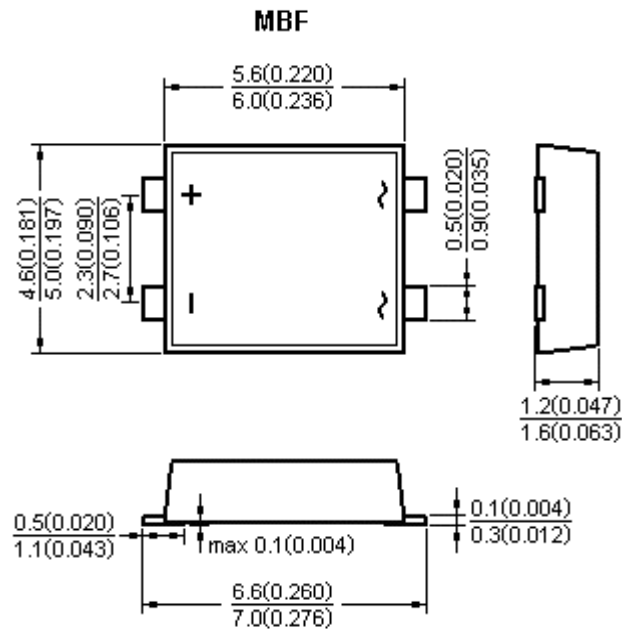
**Fig.3 Typical Instantaneous Forward Characteristics**



**Fig.4 Typical Reverse Characteristics**



### Package Outline



Dimensions in millimeters and (inches)

### Notice

- Product is intended for use in general electronics applications, especially applicable to energy conservation electronic ballast of fluorescent lamp.
- Product should be worked less than the ratings; if exceeded, may cause permanent damage or introduce latent failure mechanisms.
- The absolute maximum ratings are rated values and must not be exceeded during operation. The following are the general derating methods you design a circuit with a device.

$I_{F(AV)}$  : We recommend that the worst case current be no greater than 80% .

$T_J$  : Derate this rating when using a device in order to ensure high reliability. We recommend that the device be used at a  $T_J$  of below 125°C.

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